

First International Workshop in Nano-Packaging

With a focus on

Nano & Wafer Level Packaging

**Grand Hyatt Hotel
Atlanta, Georgia, USA
March 22-23, 2004**

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Nano and Bio-Packaging

Nano Package Design
Nano Bio-Packaging
Nano Sensor Packaging
Nano Packaging Materials & Processes
Nano Dielectrics, Capacitors & Fluidics
Nano Interconnections and Wiring
Nano Thermal Science
Nano Optical Interconnections
Nano Batteries

Wafer Level Packaging

Wafer Package Design
Materials & Processes
Burn-In and Test
Reliability & Thermomechanical Modeling
Ultra High Density Substrates
New Wafer Packaging Technologies

Abstract Submission:

Please send your title and abstract (300 words)
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October 1, 2003

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